MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS
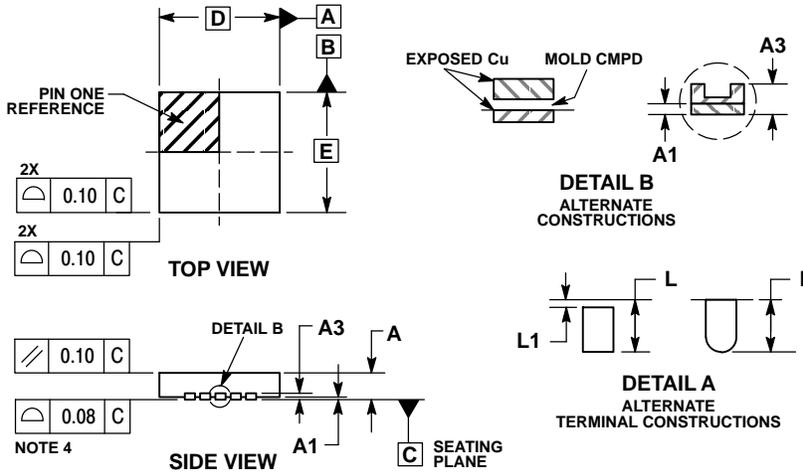
ON Semiconductor®

QFN20 4x4, 0.5P
CASE 485EE
ISSUE A

DATE 20 NOV 2015

SCALE 2:1

PIN ONE REFERENCE

TOP VIEW

2X | 0.10 | C
2X | 0.10 | C

EXPOSED Cu   MOLD CMPD

DETAIL B
ALTERNATE CONSTRUCTIONS

A3
A1

DETAIL B   A3   A

0.10 | C
0.08 | C

NOTE 4

SIDE VIEW

A1   C SEATING PLANE

L   L
L1

DETAIL A
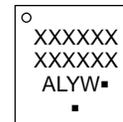**ALTERNATE TERMINAL CONSTRUCTIONS**

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

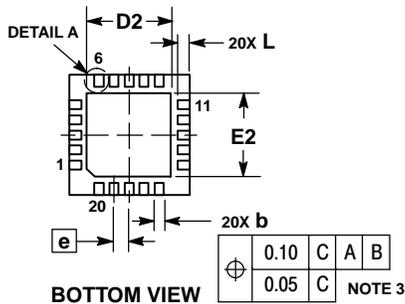| DIM | MILLIMETERS | |
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.25	0.35
D	4.00 BSC	
D2	2.75	2.85
E	4.00 BSC	
E2	2.75	2.85
e	0.50 BSC	
L	0.25	0.35
L1	0.00	0.15

DETAIL A   D2   20X L

6
11
E2
1
20   20X b
e

BOTTOM VIEW

⊕ | 0.10 | C | A | B
⊕ | 0.05 | C

NOTE 3

GENERIC MARKING DIAGRAM*

XXXXX
XXXXX
ALYW■
■
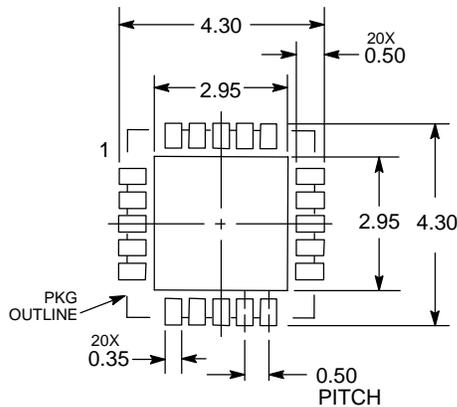
XXXXXX= Specific Device Code
A   = Assembly Location
L   = Wafer Lot
Y   = Year
W   = Work Week
■   = Pb−Free Package
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ■", may or may not be present.

SOLDERING FOOTPRINT*

4.30
20X 0.50
2.95
1
2.95   4.30
PKG OUTLINE
20X 0.35
0.50 PITCH

DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN20 4X4, 0.5P	PAGE 1 OF 2

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